

Power management (dual transistors)

EMF32 / UMF32N

DTA143T and 2SK3019 are housed independently in a EMT6 package.

Application

Power management circuit

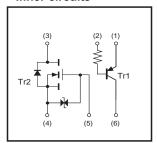
● Features

- 1) Power switching circuit in a single package.
- 2) Mounting cost and area can be cut in half.

Structure

Silicon epitaxial planar transistor

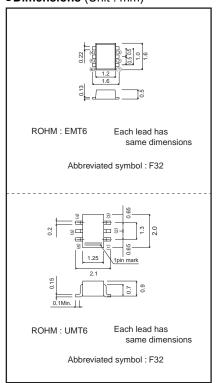
•Inner circuits



Packaging specifications

Туре	EMF32	UMF32N
Package	EMT6	UMT6
Marking	F32	F32
Code	T2R	TR
Basic ordering unit (pieces)	8000	3000

●Dimensions (Unit : mm)



EMF32 / UMF32N Data Sheet

●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-base voltage	Vсво	-50	V
Collector-emitter voltage	Vceo	-50	V
Emitter-base voltage	Vево	-5	V
Collector current	Ic	-100	mA
Power dissipation	Pc	150(TOTAL)	mW *1
Junction temperature	Tj	150	°C
Range of storage temperature	Tstg	-55 to +150	°C

^{*1 120}mW per element must not be exceeded. Each terminal mounted on a recommended land.

Tr2

Parameter		Symbol	Limits	Unit
Drain-source voltage		VDSS	30	V
Gate-source voltage		Vgss	±20	V
Drain current	Continuous	ΙD	100	mA
	Pulsed	IDP	200	mA *1
Reverse drain current	Continuous	Idr	100	mA
	Pulsed	IDRP	200	mA *1
Total power dissipation		P□	150(TOTAL)	mW *2
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

●Electrical characteristics (Ta=25°C) Tr1

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Collector-base breakdown voltage	ВУсво	-50	-	-	V	Ic= -50μA
Collector-emitter breakdown voltage	BVceo	-50	-	-	V	Ic=-1mA
Emitter-base breakdown voltage	ВУево	-5	-	-	V	Iε= -50μA
Collector cutoff current	Ісво	-	-	-0.5	μΑ	Vcb= -50V
Emitter cutoff current	ІЕВО	-	-	-0.5	μΑ	V _{EB} = -4V
Collector-emitter saturation voltage	VCE(sat)	-	-	-0.3	V	Ic/I _B = -5mA/ -0.25mA
DC current transfer ratio	hfe	100	250	600	-	Ic=-1mA, Vc==-5V
Input resistance	R ₁	3.29	4.7	6.11	kΩ	_
Transition frequency	f⊤	-	250	-	MHz	Vc=-10V, Ie=5mA, f=100MHz *

^{*} Transition frequency of the device

Tr2

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	_	_	±1	μΑ	Vgs=±20V, Vps=0V	
Drain-source breakdown voltage	V(BR)DSS	30	_	_	V	In=10μA, Vgs=0V	
Zero gate voltage drain current	IDSS	_	_	1.0	μΑ	V _{DS} =30V, V _{GS} =0V	
Gate-threshold voltage	VGS(th)	0.8	_	1.5	V	Vps=3V, Ip=100μA	
Static drain-source on-state resistance	RDS(on)	_	5	8	Ω	In=10mA, Vgs=4V	
		_	7	13	Ω	ID=1mA, VGS=2.5V	
Forward transfer admittance	Yfs	20	_	-	ms	VDS=3V, ID=10mA	
Input capacitance	Ciss	_	13	-	pF		
Output capacitance	Coss	_	9	-	pF	V _{DS} =5V, V _{GS} =0V, f=1MHz	
Reverce transfer capacitance	Crss	_	4	_	pF	1	
Turn-on delay time	td(on)	_	15	_	ns		
Rise time	tr	_	35	-	ns	ID=10mA, VDD ≒5V,	
Turn-off delay time	td(off)	_	80	_	ns	Vgs=5V, Rl=500 Ω , Rgs=10 Ω	
Fall time	tr	_	80	_	ns	1700-1022	

^{*1} PW:10ms Duty cycle≤50%
*2 120mW per element must not be exceeded. Each terminal mounted on a recommended land.

EMF32 / UMF32N Data Sheet

•Electrical characteristic curves

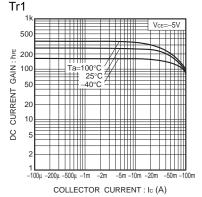


Fig.1 DC current gain vs. collector current

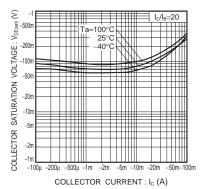


Fig.2 Collector-emitter saturation voltage vs. collector current

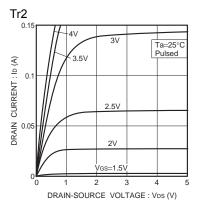


Fig.3 Typical output characteristics

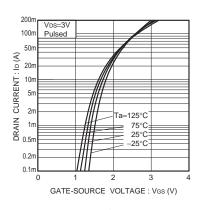


Fig.4 Typical transfer characteristics

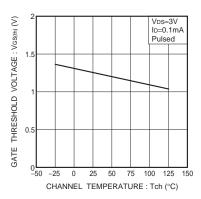


Fig.5 Gate threshold voltage vs. channel temperature

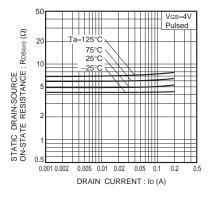


Fig.6 Static drain-source on-state resistance vs. drain current (I)

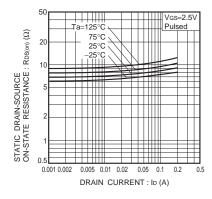


Fig.7 Static drain-source on-state resistance vs. drain current (II)

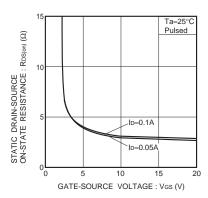


Fig.8 Static drain-source on-state resistance vs. gate-source voltage

EMF32 / UMF32N Data Sheet

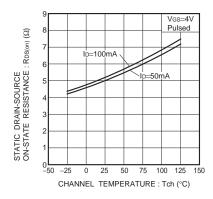


Fig.9 Static drain-source on-state resistance vs. channel temperature

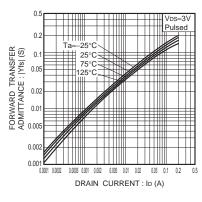


Fig.10 Forward transfer admittance vs. drain current

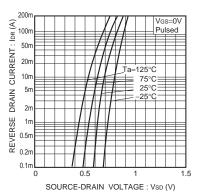


Fig.11 Reverse drain current vs. source-drain voltage (I)

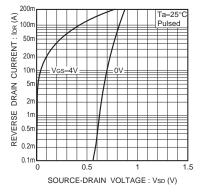


Fig.12 Reverse drain current vs. source-drain voltage (II)

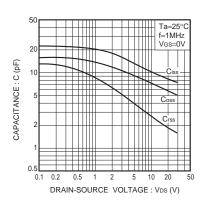


Fig.13 Typical capacitance vs. drain-source voltage

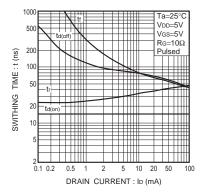


Fig.14 Switching characteristics

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